

**PATENT ASSIGNMENT**

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Reid C. Danielson	01/09/2007
<b>RECEIVING PARTY DATA</b>	
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<b>City:</b>	Hutchinson
<b>State/Country:</b>	MINNESOTA
<b>Postal Code:</b>	55350-9784
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11622167
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<b>Total Attachments: 2</b> source=HTIASSIGNMENT343994#page1.tif source=HTIASSIGNMENT343994#page2.tif	

OP \$40.00 11622167

## ASSIGNMENT

WHEREAS, I, Reid C. Danielson, of 15303 43rd Street Southwest, Cokato, MN 55321, have invented certain new and useful improvements in SHIELDED COPPER-DIELECTRIC FLEXURE FOR DISK DRIVE HEAD SUSPENSIONS, in which an application is about to be made for Letters Patent of the United States, said application having been executed on even date herewith, and which may be identified in the United States Patent Office by Serial No. \_\_\_\_\_, filed \_\_\_\_\_, and

WHEREAS, Hutchinson Technology Incorporated, Corporation of the State of Minnesota, and having an address of 40 West Highland Park Drive N.E., Hutchinson, MN 55350-9784 United States, is desirous of acquiring the entire right, title and interest in and to said invention, said application and in, to and under any and all Letters Patent to be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the said Hutchinson Technology Incorporated, its successors and assigns, the entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all rights under the International Convention, and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to the above-mentioned assignee in accordance herewith.

I Hereby Authorize the above-mentioned assignee, its successors and assigns or anyone it may properly designate, to insert in this instrument the filing date and Serial Number of said application when ascertained.

I Further Authorize said assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent, in its own name, if desired, in any and all foreign countries, and additionally to claim the filing date of said United States application and/or otherwise take advantage of the provisions of the International Convention.

I do hereby covenant and agree with the said assignee, its successors and assigns, that I will not execute any writing or do any act whatsoever conflicting with these presents, and that I or my executors or administrators will, at any time upon request, without further or additional consideration, but at the expense of said assignee, its successors and assigns, execute such additional writings and do such additional acts as said assignee, its successors and assigns, may deem necessary or desirable to perfect the assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

